

Title (en)  
FLIP-CHIP BONDED IMAGER DIE

Title (de)  
AN BILDGEBERMATRIZE GEBONDETER FLIP-CHIP

Title (fr)  
PUCE D'IMAGEUR À CONNEXION PAR BILLES

Publication  
**EP 2745324 A2 20140625 (EN)**

Application  
**EP 12768926 A 20120820**

Priority  
• US 201161525372 P 20110819  
• US 2012051573 W 20120820

Abstract (en)  
[origin: WO2013028616A2] An image sensor includes an imager die, a circuit board, and an optical layer. The circuit board is flip-chip bonded to the imager die. The optical layer is adhered to the circuit board and includes a first portion configured to refract light differently than a second portion. Both the first portion and the second portion are integrally formed with the optical layer.

IPC 8 full level  
**H01L 27/146** (2006.01)

CPC (source: EP)  
**H01L 27/14618** (2013.01); **H01L 2924/0002** (2013.01); **H04N 23/54** (2023.01); **H04N 23/57** (2023.01)

Citation (search report)  
See references of WO 2013028616A2

Designated contracting state (EPC)  
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DOCDB simple family (publication)  
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